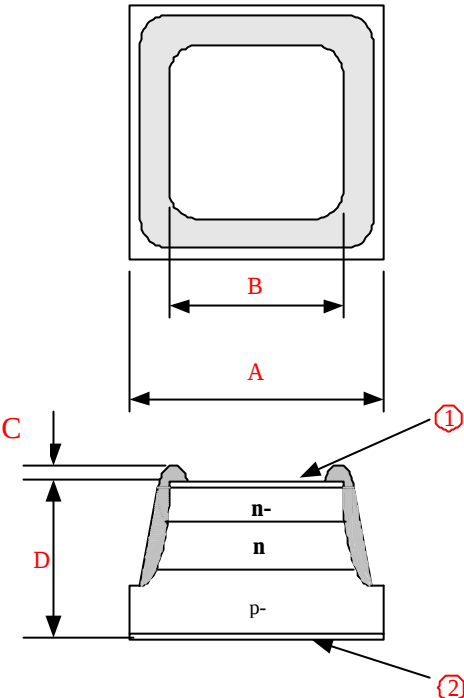


Product STD GPP(N side Mesa) Customer : Wai Semicorn Customer Part. No: 1895	Type 8GXNSP221-0400									
Metallization Top Gold ① Bottom Nickel ②										
Dimension in mils <table border="1" data-bbox="77 469 566 836"> <thead> <tr> <th></th><th>Dimension</th></tr> </thead> <tbody> <tr> <td>A</td><td>87 ± 2</td></tr> <tr> <td>B</td><td>65 (MIN.)</td></tr> <tr> <td>C</td><td>2 (MAX.)</td></tr> <tr> <td>D</td><td>9± 1.5</td></tr> </tbody> </table>			Dimension	A	87 ± 2	B	65 (MIN.)	C	2 (MAX.)	D
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Absolute Maximum Ratings (Ta=25?)

Electrical Characteristics

Item	Symbol	Test Condition	Min.	Max.	Remark
FORWARD VOLTAGE	VF	IF=3A		0.97 V	Sample size 50 ea / 1lot
REVERSE CURRENT	IR	VR=400V		1μA	
BREAKDOWN VOLTAGE	BVR	IR=5μA	440V		
REVERSE RECOVERY TIME	TRR	RG1	1200ns		
TOTAL ELEC.YIELD (CHIP TEST)	BVR/VF/IR		98%		

Dice yield within wafer >90%